



Electrical Modeling and Design for 3D System Integration: 3D Integrated Circuits and Packaging, Signal Integrity, Power Integrity and EMC

Er-Ping Li

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New advanced modeling methods for simulating the electromagnetic properties of complex three-dimensional electronic systems

Based on the author's extensive research, this book sets forth tested and proven electromagnetic modeling and simulation methods for analyzing signal and power integrity as well as electromagnetic interference in large complex electronic interconnects, multilayered package structures, integrated circuits, and printed circuit boards. Readers will discover the state of the technology in electronic package integration and printed circuit board simulation and modeling. In addition to popular full-wave electromagnetic computational methods, the book presents new, more sophisticated modeling methods, offering readers the most advanced tools for analyzing and designing large complex electronic structures.

Electrical Modeling and Design for 3D System Integration begins with a comprehensive review of current modeling and simulation methods for signal integrity, power integrity, and electromagnetic compatibility. Next, the book guides readers through:

- The macromodeling technique used in the electrical and electromagnetic modeling and simulation of complex interconnects in three-dimensional integrated systems
- The semi-analytical scattering matrix method based on the N-body scattering theory for modeling of three-dimensional electronic package and multilayered printed circuit boards with multiple vias
- Two- and three-dimensional integral equation methods for the analysis of power distribution networks in three-dimensional package integrations
- The physics-based algorithm for extracting the equivalent circuit of a complex power distribution network in three-dimensional integrated systems and printed circuit boards
- An equivalent circuit model of through-silicon vias
- Metal-oxide-semiconductor capacitance effects of through-silicon vias

Engineers, researchers, and students can turn to this book for the latest techniques and methods for the electrical modeling and design of electronic packaging, three-dimensional electronic integration, integrated circuits, and printed circuit boards.

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Patricia Howland:

The reason why? Because this Electrical Modeling and Design for 3D System Integration: 3D Integrated Circuits and Packaging, Signal Integrity, Power Integrity and EMC is an unordinary book that the inside of the publication waiting for you to snap the idea but latter it will shock you with the secret the idea inside. Reading this book alongside it was fantastic author who also write the book in such incredible way makes the content on the inside easier to understand, entertaining technique but still convey the meaning entirely. So , it is good for you for not hesitating having this nowadays or you going to regret it. This unique book will give you a lot of positive aspects than the other book have got such as help improving your ability and your critical thinking technique. So , still want to hold up having that book? If I were being you I will go to the reserve store hurriedly.

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